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**What Are Embedded - Microcontrollers - Application Specific?**

Application specific microcontrollers are engineered to

#### Details

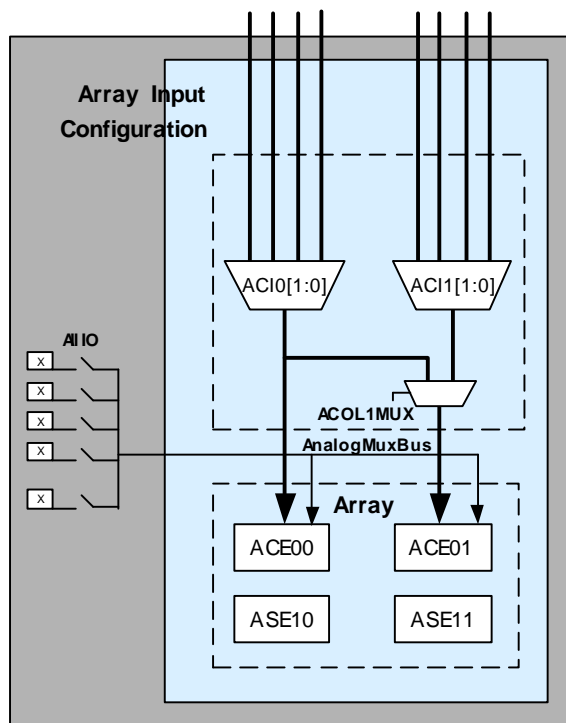
Product Status	Obsolete
Applications	Touchscreen Controller
Core Processor	M8C
Program Memory Type	FLASH (8kB)
Controller Series	CY8CT
RAM Size	512 x 8
Interface	I <sup>2</sup> C, SPI, UART
Number of I/O	-
Voltage - Supply	2.4V ~ 5.25V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8ctmg110-32ltxi">https://www.e-xfl.com/product-detail/infineon-technologies/cy8ctmg110-32ltxi</a>

## The Analog System

The Analog System consists of 4 configurable blocks that allow the creation of complex analog signal flows. Analog peripherals are very flexible and may be customized to support specific application requirements. Some of the common PSoC analog functions for this device (most available as user modules) are:

- Analog-to-digital converters (single or dual, with 8-bit resolution)
- Pin-to-pin comparator
- Single-ended comparators (up to 2) with absolute (1.3V) reference or 8-bit DAC reference
- 1.3V reference (as a System Resource)

**Figure 2. Analog System Block Diagram**



## The Analog Multiplexer System

The Analog Mux Bus connects to every GPIO pin. Pins are connected to the bus individually or in any combination. The bus also connects to the analog system for capacitive sensing with the TrueTouch block comparator. An additional 8:1 analog input multiplexer provides a second path to bring Port 0 pins to the analog array.

Switch control logic enables selected pins to switch dynamically under hardware control. This allows capacitive measurement for the touchscreen application. Other multiplexer applications include:

- Chip-wide mux that allows analog input from any IO pin.
- Electrical connection between any IO pin combinations.

## Additional System Resources

System Resources, some of which are listed in the previous sections, provide additional capability useful to complete systems. Additional resources include low voltage detection and power on reset. Brief statements describing the merits of each system resource follow.

- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks may be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.
- The I2C module provides 100 and 400 kHz communication over two wires. Slave, master, and multi-master modes are all supported.
- Low Voltage Detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced POR (Power On Reset) circuit eliminates the need for a system supervisor.
- An internal 1.3 voltage reference provides an absolute reference for the analog system, including ADCs and DACs.
- Versatile analog multiplexer system.

## Getting Started

To understand the TrueTouch device, read this data sheet and use the PSoC Designer™ Integrated Development Environment (IDE). This data sheet is an overview of the general silicon information and electrical specifications. For in depth touchscreen application information, including touchscreen specific specifications, read the touchscreen user module data sheet that is supported by this specific device.

### TrueTouch Device Characteristics

Depending on your TrueTouch device selected for a touchscreen application, characteristics and capabilities of each device changes. Table 1 lists the touchscreen sensing capabilities available for specific TrueTouch devices. The TrueTouch device covered by this data sheet is highlighted in this table.

**Table 1. TrueTouch Device Characteristics**

TrueTouch Part Number	Sensor Inputs	Max Screen Size (Inches)	Single-Touch	Multi-Touch Gesture	Multi-Touch All-Point	Scan Speed (ms) <sup>[1]</sup>	Current Consumption <sup>[2]</sup>	Flash Size	SRAM Size
CY8CTST110	up to 24	4.3"	Y	N	N	0.5	3	8K	512 Bytes
CY8CTST120	up to 44	8.4"	Y	N	N	0.5	16	16K	1K
CY8CTMG110	up to 24	4.3"	Y	Y	N	0.5	3	8K	512 Bytes
CY8CTMG120	up to 44	8.4"	Y	Y	N	0.5	16	16K	1K
CY8CTMA120	up to 37	7.3"	Y	Y	Y	0.12	16	16K	1K

## Development Kits

Development Kits are available from the following distributors: Digi-Key, Avnet, Arrow, and Future. The Cypress Online Store contains development kits, C compilers, and all accessories for PSoC development. Go to the Cypress Online Store web site at <http://www.cypress.com>, click the Online Store shopping cart icon at the bottom of the web page, and click *PSoC (Programmable System-on-Chip)* to view a current list of available items.

## Technical Training Modules

Free PSoC technical training modules are available for users new to PSoC. Training modules cover designing, debugging, advanced analog, and CapSense. Go to <http://www.cypress.com/training>.

## Consultants

Certified PSoC Consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC Consultant go to <http://www.cypress.com>, click on Design Support located on the left side of the web page, and select CYPros Consultants.

## Technical Support

PSoC application engineers take pride in fast and accurate response. They are available with a four hour guaranteed response at <http://www.cypress.com/support>.

## Application Notes

A long list of application notes can assist you in every aspect of your design effort. To view the PSoC application notes, go to the <http://www.cypress.com> web site and select Application Notes under the Design Resources list located in the center of the web page. Application notes are sorted by date by default.

## Development Tools

PSoC Designer is a Microsoft® Windows based, integrated development environment for the Programmable System-on-Chip (PSoC) devices. The PSoC Designer IDE and application runs on Windows NT 4.0, Windows 2000, Windows Millennium (Me), or Windows XP (see Figure 3 on page 5).

PSoC Designer helps the customer to select an operating configuration for the PSoC, write application code that uses the PSoC, and debug the application. This system provides design database management by project, an integrated debugger with In-Circuit Emulator, in-system programming support, and the CYASM macro assembler for the CPUs.

PSoC Designer also supports a high level C language compiler developed specifically for the devices in the family.

### Notes

1. Per sensor typical. Depends on touchscreen panel. For MA120 per X/Y crossing  $V_{cc} = 3.3V$ .
2. Average mA supply current. Based on 8 ms report rate, except for MA120.

## Designing with User Modules

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC blocks. They implement a wide variety of user selectable functions. Each block has several registers that determine its function and connectivity to other blocks, multiplexers, buses and to the IO pins. Iterative development cycles permit you to adapt the hardware and the software. This substantially lowers the risk of selecting a different part to meet the final design requirements.

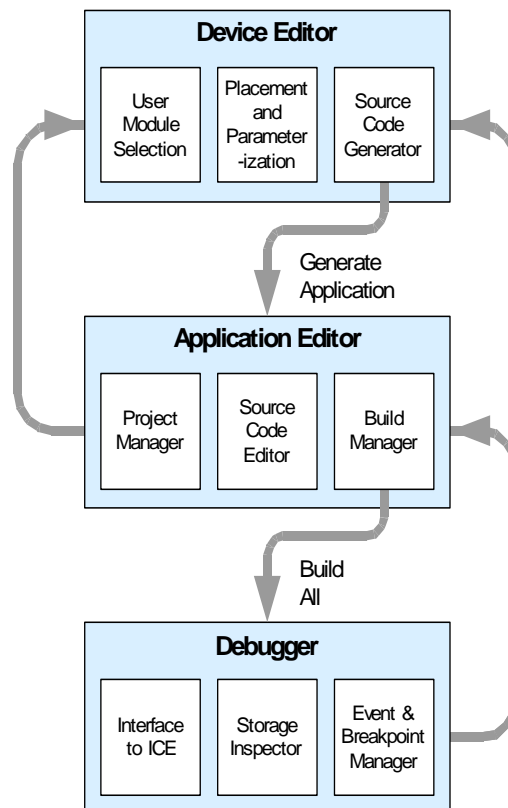
To speed the development process, the PSoC Designer IDE provides a library of pre-built, pre-tested hardware peripheral functions, called "User Modules." User modules make selecting and implementing peripheral devices simple. They come in analog, digital, and mixed signal varieties. The standard user module library contains over 50 common peripherals such as ADCs, DACs, timers, counters, UARTs, and other uncommon peripherals, such as DTMF Generators and Bi-Quad analog filter sections.

Each user module establishes the basic register settings to implement the selected function. It also provides parameters that allow you to tailor its precise configuration to a particular application. For example, a Pulse Width Modulator User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit to establish the pulse width and duty cycle. User modules also provide tested software to cut your development time. The user module application programming interface (API) provides high level functions to control and respond to hardware events at run time. The API also provides optional interrupt service routines to adapt as needed.

The API functions are documented in user module data sheets that are viewed directly in the PSoC Designer IDE. These data sheets explain the internal operation of the user module and provide performance specifications. Each data sheet describes the use of each user module parameter and documents the setting of each register controlled by the user module.

The development process starts when you open a new project and bring up the Device Editor, a graphical user interface (GUI) for configuring the hardware. Select the user modules you need for your project and map them onto the PSoC blocks with point-and-click simplicity. Next, you build signal chains by inter-connecting user modules to each other and the IO pins. At this stage, also configure the clock source connections and enter parameter values directly or by selecting values from drop down menus. When you are ready to test the hardware configuration or move on to developing code for the project, perform the "Generate Application" step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the high level user module API functions.

**Figure 4. User Module and Source Code Development Flows**



The next step is to write your main program, and any sub-routines using PSoC Designer's Application Editor subsystem. The Application Editor includes a Project Manager that allows you to open the project source code files (including all generated code files) from a hierarchal view. The source code editor provides syntax coloring and advanced edit features for both C and assembly language. File search capabilities include simple string searches and recursive "grep-style" patterns. A single mouse click invokes the Build Manager. It employs a professional-strength "makefile" system to automatically analyze all file dependencies and run the compiler and assembler as necessary. Project-level options control optimization strategies used by the compiler and linker. Syntax errors are displayed in a console window. Double click the error message to show the offending line of source code. When all is correct, the linker builds a HEX file image suitable for programming.

The last step in the development process takes place inside the PSoC Designer's Debugger subsystem. The Debugger downloads the HEX image to the In-Circuit Emulator (ICE) where it runs at full speed. Debugger capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint and watch-variable features, the Debugger provides a large trace buffer. This enables to define complex breakpoint events such as monitoring address and data bus values, memory locations, and external signals.

## Document Conventions

### Acronyms Used

The following table lists the acronyms that are used in this document.

Acronym	Description
AC	alternating current
ADC	analog-to-digital converter
API	application programming interface
CPU	central processing unit
CT	continuous time
DAC	digital-to-analog converter
DC	direct current
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
FSR	full scale range
GPIO	general purpose IO
GUI	graphical user interface
HBM	human body model
ICE	in-circuit emulator
ILO	internal low speed oscillator
IMO	internal main oscillator
IO	input/output
IPOR	imprecise power on reset
LSb	least-significant bit
LVD	low voltage detect
MSb	most-significant bit
PC	program counter
PLL	phase-locked loop
POR	power on reset
PPOR	precision power on reset
PSoC®	Programmable System-on-Chip™
PWM	pulse width modulator
SC	switched capacitor
SLIMO	slow IMO
SMP	switch mode pump
SRAM	static random access memory

### Units of Measure

A units of measure table is located in the Electrical Specifications section. [Table 4](#) on page 12 lists all the abbreviations used to measure the PSoC devices.

### Numeric Naming

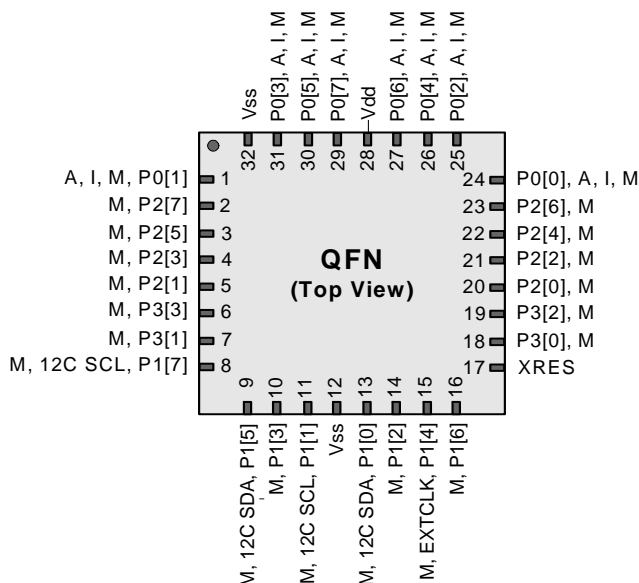
Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers are also represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or 0x are decimal.

## Pinouts

The CY8CTMG110 TrueTouch device is available in a 32-pin QFN package which is listed in the following tables. Every port pin (labeled with a "P") is capable of Digital IO and connection to the common analog bus. However, Vss, Vdd, SMP, and XRES are not capable of Digital IO.

### 32-Pin Part Pinout

**Figure 5. CY8CTMG110 32-Pin Sawn TrueTouch Device**



**Table 2. Pin Definitions - CY8CTMG110 32-Pin (QFN)**

Pin No.	Type		Name	Description
	Digital	Analog		
1	IO	I, M	P0[1]	Analog column mux input.
2	IO	M	P2[7]	
3	IO	M	P2[5]	
4	IO	M	P2[3]	
5	IO	M	P2[1]	
6	IO	M	P3[3]	
7	IO	M	P3[1]	
8	IO	M	P1[7]	I2C Serial Clock (SCL).
9	IO	M	P1[5]	I2C Serial Data (SDA).
10	IO	M	P1[3]	
11	IO	M	P1[1]	I2C Serial Clock (SCL), ISSP-SCLK <sup>[3]</sup> .
12	Power		Vss	Ground. Connect to circuit ground.
13	IO	M	P1[0]	I2C Serial Data (SDA), ISSP-SDATA <sup>[3]</sup> .
14	IO	M	P1[2]	
15	IO	M	P1[4]	Optional External Clock Input (EXTCLK).
16	IO	M	P1[6]	
17	Input		XRES	Active high external reset with internal pull down.
18	IO	M	P3[0]	
19	IO	M	P3[2]	

**Table 2. Pin Definitions - CY8CTMG110 32-Pin (QFN) (continued)**

Pin No.	Type		Name	Description
	Digital	Analog		
20	IO	M	P2[0]	
21	IO	M	P2[2]	
22	IO	M	P2[4]	
23	IO	M	P2[6]	
24	IO	I, M	P0[0]	Analog column mux input.
25	IO	I, M	P0[2]	Analog column mux input.
26	IO	I, M	P0[4]	Analog column mux input.
27	IO	I, M	P0[6]	Analog column mux input.
28	Power		Vdd	Supply voltage. Bypass to ground with 0.1 uF capacitor.
29	IO	I, M	P0[7]	Analog column mux input.
30	IO	I, M	P0[5]	Analog column mux input.
31	IO	I, M	P0[3]	Analog column mux input.
32	Power		Vss	Ground. Connect to circuit ground.
EP	Power		Vss	Exposed pad is internally connected to ground. Connect to circuit ground.

**LEGEND** A = Analog, I = Input, O = Output, and M = Analog Mux Input.

**Note**

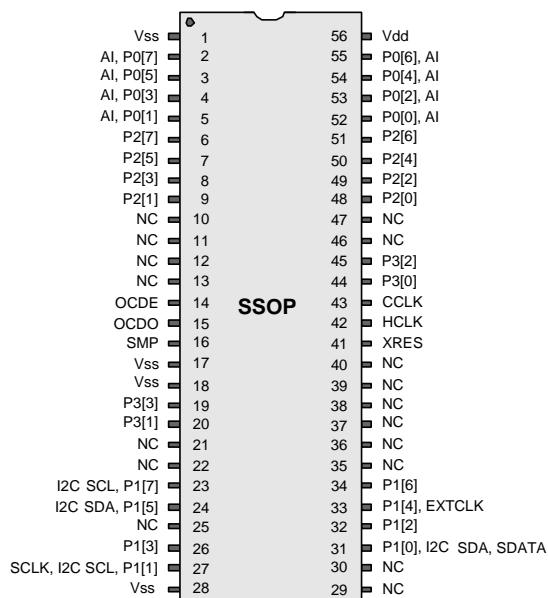
3. These are the ISSP pins, that are not High Z at POR (Power On Reset). See the *PSoC Mixed Signal Array Technical Reference Manual* for details.

## 56-Pin Part Pinout

The 56-pin SSOP part is for the CY8CTMG110 On-Chip Debug (OCD) TrueTouch device.

**Note** This part is only used for in-circuit debugging. It is NOT available for production.

**Figure 6. CY8CTMG110 56-Pin TrueTouch Device**



**Table 3. Pin Definitions - CY8CTMG110 56-Pin (SSOP)**

Pin No.	Type		Pin Name	Description
	Digital	Analog		
1	Power		Vss	Ground. Connect to circuit ground.
2	IO	I	P0[7]	Analog column mux input.
3	IO	I	P0[5]	Analog column mux input and column output.
4	IO	I	P0[3]	Analog column mux input and column output.
5	IO	I	P0[1]	Analog column mux input.
6	IO		P2[7]	
7	IO		P2[5]	
8	IO	I	P2[3]	Direct switched capacitor block input.
9	IO	I	P2[1]	Direct switched capacitor block input.
10			NC	No connection. Leave floating.
11			NC	No connection. Leave floating.
12			NC	No connection. Leave floating.
13			NC	No connection. Leave floating.
14	OCD		OCDE	OCD even data IO.
15	OCD		OCDO	OCD odd data output.
16	Power		SMP	Switch Mode Pump (SMP) connection to required external components.
17	Power		Vss	Ground. Connect to circuit ground.
18	Power		Vss	Ground. Connect to circuit ground.
19	IO		P3[3]	



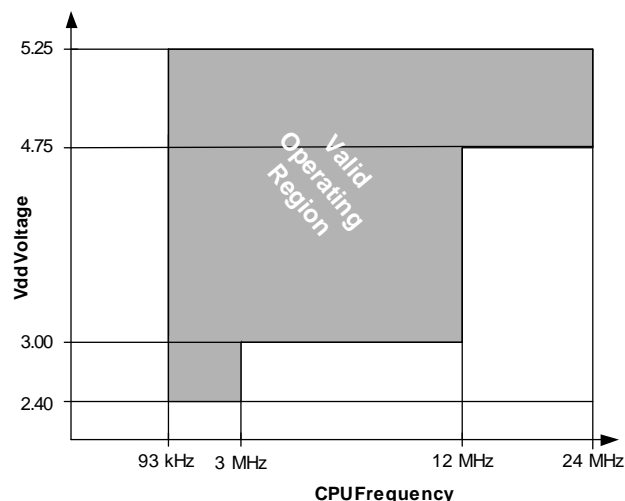
## Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8CTMG110 TrueTouch device. For up to date electrical specifications, visit the web site <http://www.cypress.com/psoc>.

Specifications are valid for  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$  and  $T_J \leq 100^{\circ}\text{C}$  as specified, except where noted.

Refer Table 18 on page 19 for the electrical specifications on the internal main oscillator (IMO) using SLIMO mode.

**Figure 7. Voltage versus CPU Frequency**



**Figure 8. IMO Frequency Trim Options**

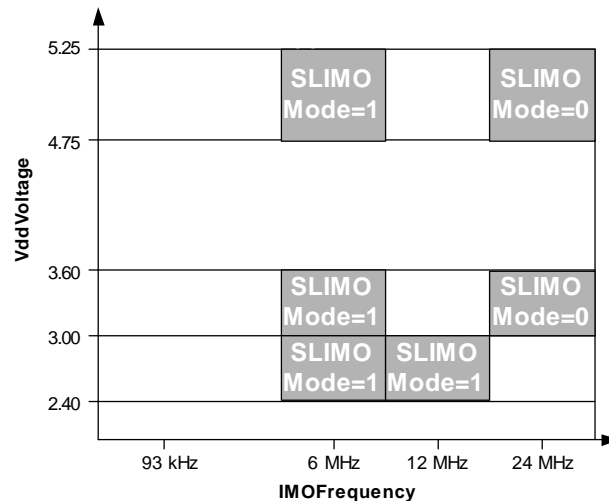


Table 4 lists the units of measure that are used in this section.

**Table 4. Units of Measure**

Symbol	Unit of Measure	Symbol	Unit of Measure
$^{\circ}\text{C}$	degree Celsius	$\mu\text{W}$	microwatts
dB	decibels	mA	milli-ampere
fF	femto farad	ms	milli-second
Hz	hertz	mV	milli-volts
KB	1024 bytes	nA	nanoampere
Kbit	1024 bits	ns	nanosecond
kHz	kilohertz	nV	nanovolts
k $\Omega$	kilohm	$\Omega$	ohm
MHz	megahertz	pA	picoampere
M $\Omega$	megaohm	pF	picofarad
$\mu\text{A}$	microampere	pp	peak-to-peak
$\mu\text{F}$	microfarad	ppm	parts per million
$\mu\text{H}$	microhenry	ps	picosecond
$\mu\text{s}$	microsecond	sps	samples per second
$\mu\text{V}$	microvolts	s	sigma: one standard deviation
$\mu\text{V}_{\text{rms}}$	microvolts root-mean-square	V	volts

**Table 8. 5V and 3.3V DC GPIO Specifications (continued)**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_H$	Input Hysteresis	–	60	–	mV	
$I_{IL}$	Input Leakage (Absolute Value)	–	1	–	nA	Gross tested to 1 $\mu$ A.
$C_{IN}$	Capacitive Load on Pins as Input	–	3.5	10	pF	Package and pin dependent. Temp = 25°C.
$C_{OUT}$	Capacitive Load on Pins as Output	–	3.5	10	pF	Package and pin dependent. Temp = 25°C.

**Table 9. 2.7V DC GPIO Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$R_{PU}$	Pull Up Resistor	4	5.6	8	k $\Omega$	
$R_{PD}$	Pull Down Resistor	4	5.6	8	k $\Omega$	
$V_{OH}$	High Output Level	$V_{DD} - 0.4$	–	–	V	$I_{OH} = 2.5$ mA (6.25 Typ), $V_{DD} = 2.4$ to 3.0V (16 mA maximum, 50 mA Typ combined $I_{OH}$ budget).
$V_{OL}$	Low Output Level	–	–	0.75	V	$I_{OL} = 10$ mA, $V_{DD} = 2.4$ to 3.0V (90 mA maximum combined $I_{OL}$ budget).
$V_{IL}$	Input Low Level	–	–	0.75	V	$V_{DD} = 2.4$ to 3.0.
$V_{IH}$	Input High Level	2.0	–	–	V	$V_{DD} = 2.4$ to 3.0.
$V_H$	Input Hysteresis	–	90	–	mV	
$I_{IL}$	Input Leakage (Absolute Value)	–	1	–	nA	Gross tested to 1 $\mu$ A.
$C_{IN}$	Capacitive Load on Pins as Input	–	3.5	10	pF	Package and pin dependent. Temp = 25°C.
$C_{OUT}$	Capacitive Load on Pins as Output	–	3.5	10	pF	Package and pin dependent. Temp = 25°C.

#### DC Operational Amplifier Specifications

Table 10, Table 11, and Table 12 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C. These are for design guidance only.

**Table 10. 5V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{OSOA}$	Input Offset Voltage (Absolute Value)	–	2.5	15	mV	
$TCV_{OSOA}$	Average Input Offset Voltage Drift	–	10	–	$\mu\text{V}/^{\circ}\text{C}$	
$I_{EBOA}^{[6]}$	Input Leakage Current (Port 0 Analog Pins)	–	200	–	pA	Gross tested to 1 $\mu$ A.
$C_{INOA}$	Input Capacitance (Port 0 Analog Pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25°C.
$V_{CMOA}$	Common Mode Voltage Range	0.0	–	$V_{DD} - 1$	V	
$G_{OLOA}$	Open Loop Gain	–	80	–	dB	
$I_{SOA}$	Amplifier Supply Current	–	10	30	$\mu$ A	

#### Note

6. Atypical behavior:  $I_{EBOA}$  of Port 0 Pin 0 is below 1 nA at 25°C; 50 nA over temperature. Use Port 0 Pins 1-7 for the lowest leakage of 200 nA.

**Table 11. 3.3V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{OSOA}$	Input Offset Voltage (absolute value)	–	2.5	15	mV	
$TCV_{OSOA}$	Average Input Offset Voltage Drift	–	10	–	$\mu V/^{\circ}C$	
$I_{EBOA}^{[6]}$	Input Leakage Current (Port 0 Analog Pins)	–	200	–	pA	Gross tested to 1 $\mu A$ .
$C_{INOA}$	Input Capacitance (Port 0 Analog Pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25°C.
$V_{CMOA}$	Common Mode Voltage Range	0	–	$V_{DD} - 1$	V	
$G_{OLOA}$	Open Loop Gain	–	80	–	dB	
$I_{SOA}$	Amplifier Supply Current	–	10	30	$\mu A$	

**Table 12. 2.7V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{OSOA}$	Input Offset Voltage (absolute value)	–	2.5	15	mV	
$TCV_{OSOA}$	Average Input Offset Voltage Drift	–	10	–	$\mu V/^{\circ}C$	
$I_{EBOA}^{[6]}$	Input Leakage Current (Port 0 Analog Pins)	–	200	–	pA	Gross tested to 1 $\mu A$ .
$C_{INOA}$	Input Capacitance (Port 0 Analog Pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25°C.
$V_{CMOA}$	Common Mode Voltage Range	0	–	$V_{DD} - 1$	V	
$G_{OLOA}$	Open Loop Gain	–	80	–	dB	
$I_{SOA}$	Amplifier Supply Current	–	10	30	$\mu A$	

#### DC Low Power Comparator Specifications

Table 13 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , 3.0V to 3.6V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , or 2.4V to 3.0V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , respectively. Typical parameters apply to 5V at 25°C. These are for design guidance only.

**Table 13. DC Low Power Comparator Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{REFLPC}$	Low Power Comparator (LPC) Reference Voltage Range	0.2	–	$V_{DD} - 1$	V	
$I_{SLPC}$	LPC Supply Current	–	10	40	$\mu A$	
$V_{OSLPC}$	LPC Voltage Offset	–	2.5	30	mV	

#### DC Analog Mux Bus Specifications

Table 14 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , 3.0V to 3.6V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , or 2.4V to 3.0V and  $-40^{\circ}C \leq T_A \leq 85^{\circ}C$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C. These are for design guidance only.

**Table 14. DC Analog Mux Bus Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$R_{SW}$	Switch Resistance to Common Analog Bus	–	–	400 800	W W	$V_{DD} \geq 2.7V$ $2.4V \leq V_{DD} \leq 2.7V$
$R_{VDD}$	Resistance of Initialization Switch to Vdd	–	–	800	W	

### DC IDAC Resolution

Table 15 lists IDAC typical resolution. Typical parameters apply to 5V at 25°C. These are for design guidance only.

Table 15. DC IDAC Resolution

Symbol	Description	Min	Typ	Max	Units	Notes
$I_{DAC}$	Current Output of 1 LSB (1x Setting)	-	90	-	nA	

### DC POR and LVD Specifications

Table 16 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C. These are for design guidance only.

Table 16. DC POR and LVD Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{PPOR0}$	Vdd Value for PPOR Trip PORLEV[1:0] = 00b	—	2.36	2.40	V	Vdd must be greater than or equal to 2.5V during startup, reset from the XRES pin, or reset from Watchdog.
$V_{PPOR1}$	PORLEV[1:0] = 01b		2.82	2.95	V	
$V_{PPOR2}$	PORLEV[1:0] = 10b		4.55	4.70	V	
$V_{LVD0}$	Vdd Value for LVD Trip VM[2:0] = 000b	2.40	2.45	2.51 <sup>[7]</sup>	V	
$V_{LVD1}$	VM[2:0] = 001b	2.85	2.92	2.99 <sup>[8]</sup>	V	
$V_{LVD2}$	VM[2:0] = 010b	2.95	3.02	3.09	V	
$V_{LVD3}$	VM[2:0] = 011b	3.06	3.13	3.20	V	
$V_{LVD4}$	VM[2:0] = 100b	4.37	4.48	4.55	V	
$V_{LVD5}$	VM[2:0] = 101b	4.50	4.64	4.75	V	
$V_{LVD6}$	VM[2:0] = 110b	4.62	4.73	4.83	V	
$V_{LVD7}$	VM[2:0] = 111b	4.71	4.81	4.95	V	
$V_{PUMP0}$	Vdd Value for PUMP Trip VM[2:0] = 000b	2.45	2.55	2.62 <sup>[9]</sup>	V	
$V_{PUMP1}$	VM[2:0] = 001b	2.96	3.02	3.09	V	
$V_{PUMP2}$	VM[2:0] = 010b	3.03	3.10	3.16	V	
$V_{PUMP3}$	VM[2:0] = 011b	3.18	3.25	3.32 <sup>[10]</sup>	V	
$V_{PUMP4}$	VM[2:0] = 100b	4.54	4.64	4.74	V	
$V_{PUMP5}$	VM[2:0] = 101b	4.62	4.73	4.83	V	
$V_{PUMP6}$	VM[2:0] = 110b	4.71	4.82	4.92	V	
$V_{PUMP7}$	VM[2:0] = 111b	4.89	5.00	5.12	V	

### Notes

7. Always greater than 50 mV above  $V_{PPOR}$  (PORLEV = 00) for falling supply.
8. Always greater than 50 mV above  $V_{PPOR}$  (PORLEV = 01) for falling supply.
9. Always greater than 50 mV above  $V_{LVD0}$ .
10. Always greater than 50 mV above  $V_{LVD3}$ .

## AC Electrical Characteristics

### AC Chip Level Specifications

Table 18 and Table 19 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 18. 5V and 3.3V AC Chip Level Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>IMO24</sub>	Internal Main Oscillator Frequency for 24 MHz	23.4	24	24.6 <sup>[12,13,14]</sup>	MHz	Trimmed for 5V or 3.3V operation using factory trim values. See Figure 8 on page 12. SLIMO mode = 0.
F <sub>IMO6</sub>	Internal Main Oscillator Frequency for 6 MHz	5.75	6	6.35 <sup>[12,13,14]</sup>	MHz	Trimmed for 5V or 3.3V operation using factory trim values. See Figure 8 on page 12. SLIMO mode = 1.
F <sub>CPU1</sub>	CPU Frequency (5V Nominal)	0.93	24	24.6 <sup>[12,13]</sup>	MHz	24 MHz only for SLIMO mode = 0.
F <sub>CPU2</sub>	CPU Frequency (3.3V Nominal)	0.93	12	12.3 <sup>[13,14]</sup>	MHz	
F <sub>BLK5</sub>	Digital PSoC Block Frequency (5V Nominal)	0	48	49.2 <sup>[12,13,15]</sup>	MHz	Refer to the AC digital block specifications.
F <sub>BLK33</sub>	Digital PSoC Block Frequency (3.3V Nominal)	0	24	24.6 <sup>[13,15]</sup>	MHz	
F <sub>32K1</sub>	Internal Low Speed Oscillator Frequency	15	32	64	kHz	
Jitter32k	32 kHz RMS Period Jitter	–	100	200	ns	
Jitter32k	32 kHz Peak-to-Peak Period Jitter	–	1400	–		
T <sub>XRST</sub>	External Reset Pulse Width	10	–	–	μs	
DC24M	24 MHz Duty Cycle	40	50	60	%	
Step24M	24 MHz Trim Step Size	–	50	–	kHz	
Fout48M	48 MHz Output Frequency	46.8	48.0	49.2 <sup>[12,14]</sup>	MHz	Trimmed. Using factory trim values.
Jitter24M1	24 MHz Peak-to-Peak Period Jitter (IMO)	–	600		ps	
F <sub>MAX</sub>	Maximum Frequency of signal on row input or row output	–	–	12.3	MHz	
T <sub>RAMP</sub>	Supply Ramp Time	0	–	–	μs	

**Table 19. 2.7V AC Chip Level Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>IMO12</sub>	Internal Main Oscillator Frequency for 12 MHz	11.5	12	12.7 <sup>[13,16,17]</sup>	MHz	Trimmed for 2.7V operation using factory trim values. See Figure 8 on page 12. SLIMO mode = 1.
F <sub>IMO6</sub>	Internal Main Oscillator Frequency for 6 MHz	5.75	6	6.35 <sup>[13,16,17]</sup>	MHz	Trimmed for 2.7V operation using factory trim values. See Figure 8 on page 12. SLIMO mode = 1.
F <sub>CPU1</sub>	CPU Frequency (2.7V Nominal)	0.093	3	3.15 <sup>[13,16]</sup>	MHz	24 MHz only for SLIMO mode = 0.
F <sub>BLK27</sub>	Digital PSoC Block Frequency (2.7V Nominal)	0	12	12.5 <sup>[13,16,17]</sup>	MHz	Refer to the AC digital block specifications.

#### Notes

12. 4.75V < V<sub>dd</sub> < 5.25V.

13. Accuracy derived from Internal Main Oscillator with appropriate trim for V<sub>dd</sub> range.

14. 3.0V < V<sub>dd</sub> < 3.6V. See Application Note AN2012 "Adjusting PSoC Microcontroller Trims for Dual Voltage-Range Operation" for information on trimming for operation at 3.3V.

15. See the individual user module data sheets for information on maximum frequencies for user modules.

### AC Low Power Comparator Specifications

Table 23 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 23. AC Low Power Comparator Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$T_{RLPC}$	LPC Response Time	–	–	50	$\mu\text{s}$	$\geq 50$ mV overdrive comparator reference set within $V_{REFLPC}$ .

### AC Analog Mux Bus Specifications

Table 24 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 24. AC Analog Mux Bus Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$F_{SW}$	Switch Rate	–	–	3.17	MHz	

### AC Digital Block Specifications

Table 25 and Table 26 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 25. 5V and 3.3V AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Units	Notes
All Functions	Maximum Block Clocking Frequency ( $> 4.75\text{V}$ )			49.2	MHz	$4.75\text{V} < V_{DD} < 5.25\text{V}$ .
	Maximum Block Clocking Frequency ( $< 4.75\text{V}$ )			24.6	MHz	$3.0\text{V} < V_{DD} < 4.75\text{V}$ .
Timer	Capture Pulse Width	50 <sup>[18]</sup>	–	–	ns	
	Maximum Frequency, No Capture	–	–	49.2	MHz	$4.75\text{V} < V_{DD} < 5.25\text{V}$ .
	Maximum Frequency, With or Without Capture	–	–	24.6	MHz	
Counter	Enable Pulse Width	50	–	–	ns	
	Maximum Frequency, No Enable Input	–	–	49.2	MHz	$4.75\text{V} < V_{DD} < 5.25\text{V}$ .
	Maximum Frequency, Enable Input	–	–	24.6	MHz	
Dead Band	Kill Pulse Width:					
	Asynchronous Restart Mode	20	–	–	ns	
	Synchronous Restart Mode	50	–	–	ns	
	Disable Mode	50	–	–	ns	
	Maximum Frequency	–	–	49.2	MHz	$4.75\text{V} < V_{DD} < 5.25\text{V}$ .
CRCPRS (PRS Mode)	Maximum Input Clock Frequency	–	–	49.2	MHz	$4.75\text{V} < V_{DD} < 5.25\text{V}$ .
CRCPRS (CRC Mode)	Maximum Input Clock Frequency	–	–	24.6	MHz	
SPIM	Maximum Input Clock Frequency	–	–	8.2	MHz	Maximum data rate at 4.1 MHz due to 2 x over clocking.
SPIS	Maximum Input Clock Frequency	–	–	4.1	MHz	
	Width of SS_ Negated Between Transmissions	50	–	–	ns	

**Note**

18. 50 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

**Table 25. 5V and 3.3V AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Units	Notes
Transmitter	Maximum Input Clock Frequency	–	–	24.6	MHz	Maximum data rate at 3.08 MHz due to 8 x over clocking. Maximum data rate at 6.15 MHz due to 8 x over clocking.
	Maximum Input Clock Frequency with Vdd ≥ 4.75V, 2 Stop Bits	–	–	49.2	MHz	
Receiver	Maximum Input Clock Frequency	–	–	24.6	MHz	Maximum data rate at 3.08 MHz due to 8 x over clocking. Maximum data rate at 6.15 MHz due to 8 x over clocking.
	Maximum Input Clock Frequency with Vdd ≥ 4.75V, 2 Stop Bits	–	–	49.2	MHz	

**Table 26. 2.7V AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Units	Notes
All Functions	Maximum Block Clocking Frequency			12.7	MHz	2.4V < Vdd < 3.0V.
Timer	Capture Pulse Width	100 <sup>[19]</sup>	–	–	ns	
	Maximum Frequency, With or Without Capture	–	–	12.7	MHz	
Counter	Enable Pulse Width	100	–	–	ns	
	Maximum Frequency, No Enable Input	–	–	12.7	MHz	
	Maximum Frequency, Enable Input	–	–	12.7	MHz	
Dead Band	Kill Pulse Width:					
	Asynchronous Restart Mode	20	–	–	ns	
	Synchronous Restart Mode	100	–	–	ns	
	Disable Mode	100	–	–	ns	
	Maximum Frequency	–	–	12.7	MHz	
CRCPRS (PRS Mode)	Maximum Input Clock Frequency	–	–	12.7	MHz	
CRCPRS (CRC Mode)	Maximum Input Clock Frequency	–	–	12.7	MHz	
SPIM	Maximum Input Clock Frequency	–	–	6.35	MHz	Maximum data rate at 3.17 MHz due to 2 x over clocking.
SPIS	Maximum Input Clock Frequency	–	–	4.1	MHz	
	Width of SS_ Negated Between Transmissions	100	–	–	ns	
Transmitter	Maximum Input Clock Frequency	–	–	12.7	MHz	Maximum data rate at 1.59 MHz due to 8 x over clocking.
Receiver	Maximum Input Clock Frequency	–	–	12.7	MHz	Maximum data rate at 1.59 MHz due to 8 x over clocking.

**Note**

19. 100 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

### AC External Clock Specifications

Table 27, Table 28, and Table 29 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 27. 5V AC External Clock Specifications**

Symbol	Description	Min	Typ	Max	Units
F <sub>OSCEXT</sub>	Frequency	0.093	–	24.6	MHz
–	High Period	20.6	–	5300	ns
–	Low Period	20.6	–	–	ns
–	Power Up IMO to Switch	150	–	–	μs

**Table 28. 3.3V AC External Clock Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>OSCEXT</sub>	Frequency with CPU Clock divide by 1	0.093	–	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F <sub>OSCEXT</sub>	Frequency with CPU Clock divide by 2 or greater	0.186	–	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High Period with CPU Clock divide by 1	41.7	–	5300	ns	
–	Low Period with CPU Clock divide by 1	41.7	–	–	ns	
–	Power Up IMO to Switch	150	–	–	μs	

**Table 29. 2.7V AC External Clock Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>OSCEXT</sub>	Frequency with CPU Clock divide by 1	0.093	–	3.08	MHz	Maximum CPU frequency is 3 MHz at 2.7V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F <sub>OSCEXT</sub>	Frequency with CPU Clock divide by 2 or greater	0.186	–	6.35	MHz	If the frequency of the external clock is greater than 3 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High Period with CPU Clock divide by 1	160	–	5300	ns	
–	Low Period with CPU Clock divide by 1	160	–	–	ns	
–	Power Up IMO to Switch	150	–	–	μs	



### AC Programming Specifications

Table 30 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 30. AC Programming Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$T_{\text{RSCLK}}$	Rise Time of SCLK	1	–	20	ns	
$T_{\text{FSCLK}}$	Fall Time of SCLK	1	–	20	ns	
$T_{\text{SSCLK}}$	Data Setup Time to Falling Edge of SCLK	40	–	–	ns	
$T_{\text{HSCLK}}$	Data Hold Time from Falling Edge of SCLK	40	–	–	ns	
$F_{\text{SCLK}}$	Frequency of SCLK	0	–	8	MHz	
$T_{\text{ERASEB}}$	Flash Erase Time (Block)	–	15	–	ms	
$T_{\text{WRITE}}$	Flash Block Write Time	–	30	–	ms	
$T_{\text{DSCLK}}$	Data Out Delay from Falling Edge of SCLK	–	–	45	ns	$3.6 < V_{\text{DD}}$
$T_{\text{DSCLK3}}$	Data Out Delay from Falling Edge of SCLK	–	–	50	ns	$3.0 \leq V_{\text{DD}} \leq 3.6$
$T_{\text{DSCLK2}}$	Data Out Delay from Falling Edge of SCLK	–	–	70	ns	$2.4 \leq V_{\text{DD}} \leq 3.0$

### AC I<sup>2</sup>C Specifications

Table 31 and Table 32 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0V to 3.6V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4V to 3.0V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at  $25^{\circ}\text{C}$ . These are for design guidance only.

**Table 31. AC Characteristics of the I<sup>2</sup>C SDA and SCL Pins for  $V_{\text{DD}} \geq 3.0\text{V}$**

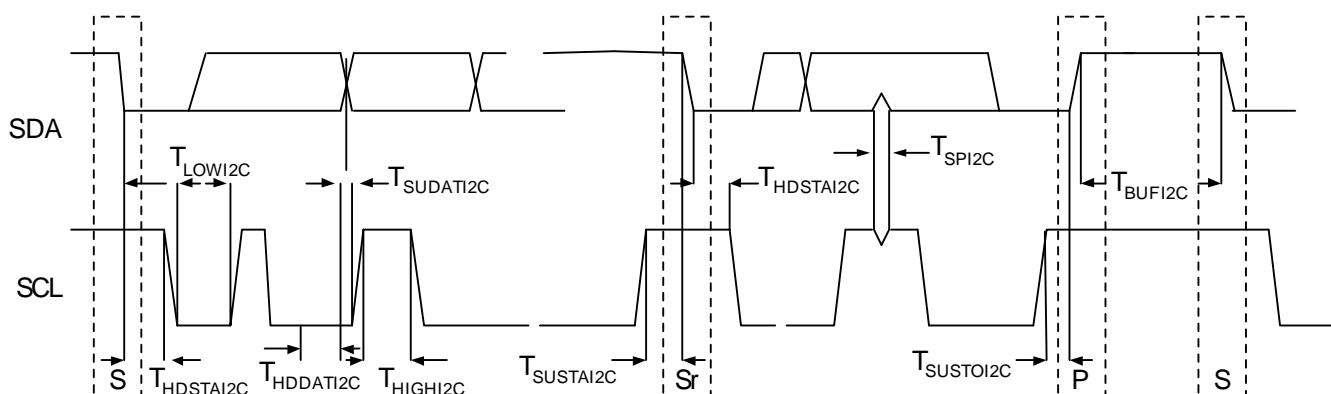
Symbol	Description	Standard Mode		Fast Mode		Units
		Min	Max	Min	Max	
$F_{\text{SCLI2C}}$	SCL Clock Frequency	0	100	0	400	kHz
$T_{\text{HDSTA12C}}$	Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	4.0	–	0.6	–	$\mu\text{s}$
$T_{\text{LOWI2C}}$	LOW Period of the SCL Clock	4.7	–	1.3	–	$\mu\text{s}$
$T_{\text{HIGHI2C}}$	HIGH Period of the SCL Clock	4.0	–	0.6	–	$\mu\text{s}$
$T_{\text{SUSTA12C}}$	Set-up Time for a Repeated START Condition	4.7	–	0.6	–	$\mu\text{s}$
$T_{\text{HDDAT12C}}$	Data Hold Time	0	–	0	–	$\mu\text{s}$
$T_{\text{SUDAT12C}}$	Data Set-up Time	250	–	100 <sup>[20]</sup>	–	ns
$T_{\text{SUSTOI2C}}$	Set-up Time for STOP Condition	4.0	–	0.6	–	$\mu\text{s}$
$T_{\text{BUF12C}}$	Bus Free Time Between a STOP and START Condition	4.7	–	1.3	–	$\mu\text{s}$
$T_{\text{SPI2C}}$	Pulse Width of Spikes are Suppressed by the Input Filter.	–	–	0	50	ns

#### Note

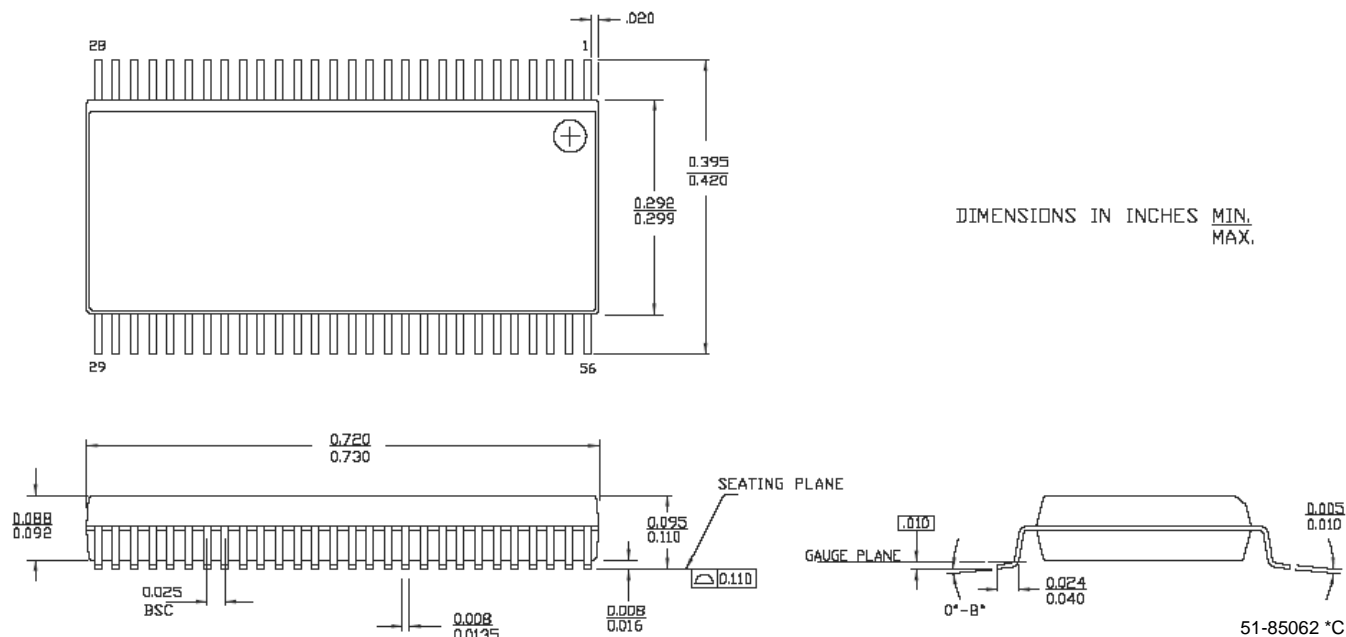
20. A Fast-Mode I<sup>2</sup>C-bus device may be used in a Standard-Mode I<sup>2</sup>C-bus system, but the requirement  $t_{\text{SU:DAT}} \geq 250$  ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line  $t_{\text{max}} + t_{\text{SU:DAT}} = 1000 + 250 = 1250$  ns (according to the Standard-Mode I<sup>2</sup>C-bus specification) before the SCL line is released.

**Table 32. 2.7V AC Characteristics of the I<sup>2</sup>C SDA and SCL Pins (Fast Mode not Supported)**

Symbol	Description	Standard Mode		Fast Mode		Units
		Min	Max	Min	Max	
F <sub>SCL I2C</sub>	SCL Clock Frequency	0	100	–	–	kHz
T <sub>HDSTAI2C</sub>	Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	4.0	–	–	–	μs
T <sub>LOWI2C</sub>	LOW Period of the SCL Clock	4.7	–	–	–	μs
T <sub>HIGHI2C</sub>	HIGH Period of the SCL Clock	4.0	–	–	–	μs
T <sub>SUSTAI2C</sub>	Setup Time for a Repeated START Condition	4.7	–	–	–	μs
T <sub>HDDATI2C</sub>	Data Hold Time	0	–	–	–	μs
T <sub>SUDATI2C</sub>	Data Setup Time	250	–	–	–	ns
T <sub>SUSTOI2C</sub>	Setup Time for STOP Condition	4.0	–	–	–	μs
T <sub>BUFI2C</sub>	Bus Free Time Between a STOP and START Condition	4.7	–	–	–	μs
T <sub>SPI2C</sub>	Pulse Width of Spikes are Suppressed by the Input Filter.	–	–	–	–	ns

**Figure 12. Definition for Timing for Fast/Standard Mode on the I<sup>2</sup>C Bus**


**Figure 14. 56-Pin (300-Mil) SSOP**



## Thermal Impedances

**Table 33. Thermal Impedances per Package**

Package	Typical $\theta_{JA}$ <sup>[21]</sup>	Typical $\theta_{JC}$
32 QFN <sup>[21]</sup> 5x5 mm 0.93 MAX	22 °C/W	12 °C/W

## Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

**Table 34. Solder Reflow Peak Temperature**

Package	Minimum Peak Temperature <sup>[23]</sup>	Maximum Peak Temperature
32 QFN	240°C	260°C

### Notes

21.  $T_J = T_A + \text{Power} \times \theta_{JA}$ .

22. To achieve the thermal impedance specified for the \*\* package, the center thermal pad is soldered to the PCB ground plane.

23. Higher temperatures is required based on the solder melting point. Typical temperatures for solder are 220 ± 50°C with Sn-Pb or 245 ± 50°C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.

## Accessories (Emulation and Programming)

### Third Party Tools

Several tools have been specially designed by the following third party vendors to accompany PSoC devices during development and production. Specific details for each of these tools can be found at <http://www.cypress.com> under Design Resources > Evaluation Boards.

### Build a PSoC Emulator into Your Board

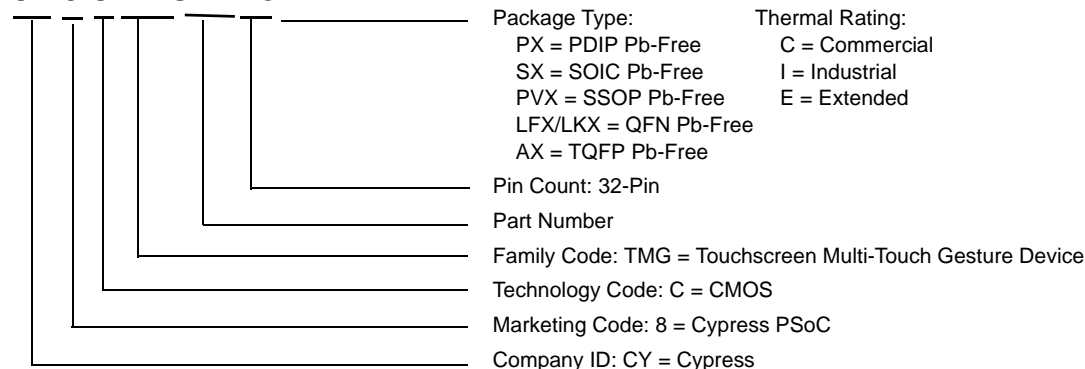
For details on how to emulate your circuit before going to volume production using an on-chip debug (OCD) non-production PSoC device, see application note [AN2323](#) "Debugging - Build a PSoC Emulator into Your Board".

## Ordering Information

Package	Ordering Code	Flash (Bytes)	SRAM (Bytes)	Temperature Range	Single-Touch Enabled	Multi-Touch Gesture Enabled	Multi-Touch All-Point Enabled	X/Y Sensor Inputs
32-Pin (5x5 mm 0.93 MAX) SAWN QFN	CY8CTMG110-32LTXI	8K	512	-40°C to +85°C	Y	Y	N	Up to 24
32-Pin (5x5 mm 0.93 MAX) SAWN QFN (Tape and Reel)	CY8CTMG110-32LTXIT	8K	512	-40°C to +85°C	Y	Y	N	Up to 24
56-Pin OCD SSOP	CY8CTMG110-00PVXI	8K	512	-40°C to +85°C	Y	Y	N	Up to 24

## Ordering Code Definitions

CY 8 C TMG xxx-32xx



## Document History Page

Document Title: CY8CTMG110 TrueTouch™ Multi-Touch Gesture Touchscreen Controller Document Number: 001-46928				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	2518134	DSO/AESA	06/18/08	New data sheet
*A	2523303	DSO/PYRS	07/01/08	Updated X/Y sensor inputs to 24 and supported screen sizes to 4.6" and below Changed operating voltage range to 2.7V to 5.25V.
*B	2549257	YOM/PYRS	08/06/08	Added other sections based on PSoC data sheets

## Sales, Solutions, and Legal Information

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USB	<a href="http://psoc.cypress.com/usb">psoc.cypress.com/usb</a>

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